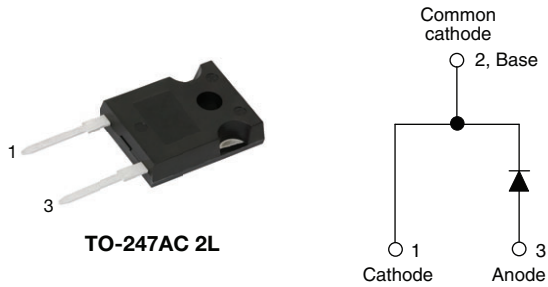


Hyperfast Rectifier, 30 A FRED Pt®



FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- Single diode device
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	30 A
V_R	600 V
V_F at I_F	1.34 V
t_{rr} typ.	See Recovery table
T_J max.	175 °C
Package	TO-247AC 2L
Circuit configuration	Single

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

MECHANICAL DATA

Case: TO-247AC 2L

Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per J-STD-002

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		600	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 116$ °C	30	A
Non-repetitive peak surge current	I_{FSM}	$T_J = 25$ °C, $t_p = 10$ ms	300	
Operating junction and storage temperatures	T_J, T_{Stg}		-65 to +175	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25$ °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100$ μ A	600	-	-	V
Forward voltage	V_F	$I_F = 30$ A	-	2.0	2.6	
		$I_F = 30$ A, $T_J = 150$ °C	-	1.34	1.75	
Reverse leakage current	I_R	$V_R = V_R$ rated	-	0.3	50	μ A
		$T_J = 150$ °C, $V_R = V_R$ rated	-	60	500	
Junction capacitance	C_T	$V_R = 600$ V	-	33	-	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body	-	3.5	-	nH



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t _{rr}	I _F = 1.0 A, di _F /dt = 50 A/μs, V _R = 30 V	-	28	35	ns
		T _J = 25 °C	-	31	-	
		T _J = 125 °C	-	77	-	
Peak recovery current	I _R RM	T _J = 25 °C	-	3.5	-	A
		T _J = 125 °C	-	7.7	-	
Reverse recovery charge	Q _{rr}	T _J = 25 °C	-	65	-	nC
		T _J = 125 °C	-	345	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C
Thermal resistance, junction to case per leg	R _{thJC}		-	0.5	0.9	°C/W
Thermal resistance, junction to ambient per leg	R _{thJA}	Typical socket mount	-	-	40	
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.4	-	
Weight			-	6.0	-	g
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-247AC 2L	30EPH06			

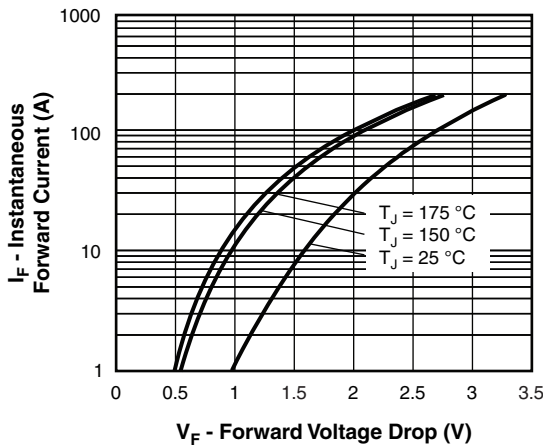


Fig. 1 - Typical Forward Voltage Drop Characteristics

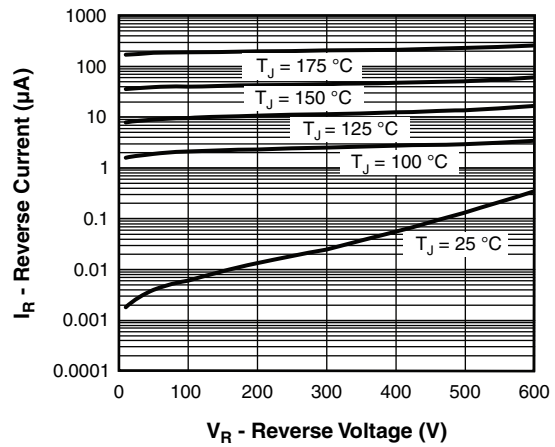


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

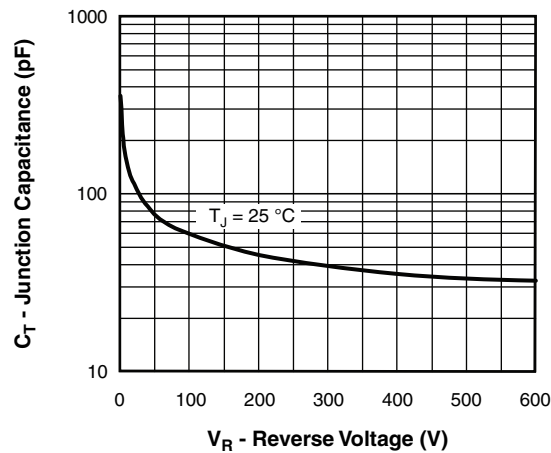


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

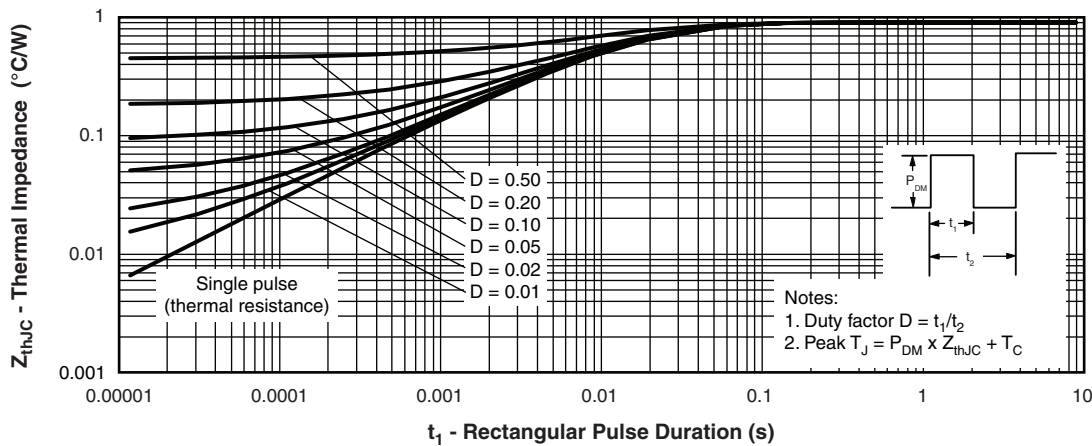


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

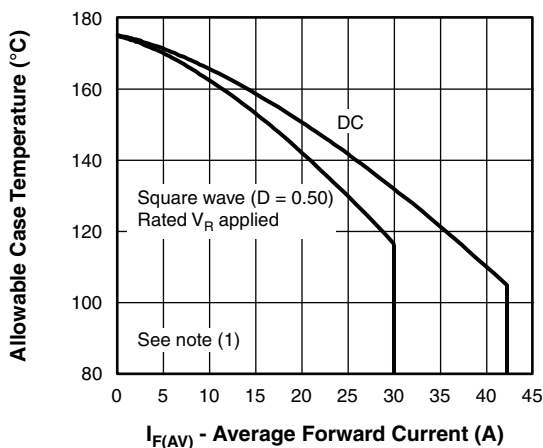


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

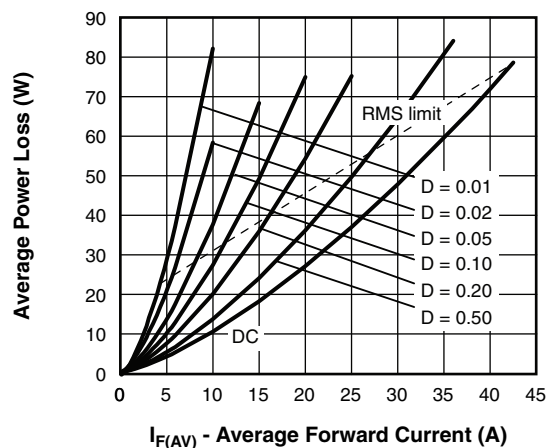


Fig. 6 - Forward Power Loss Characteristics

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
- P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
- P_{dREV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R

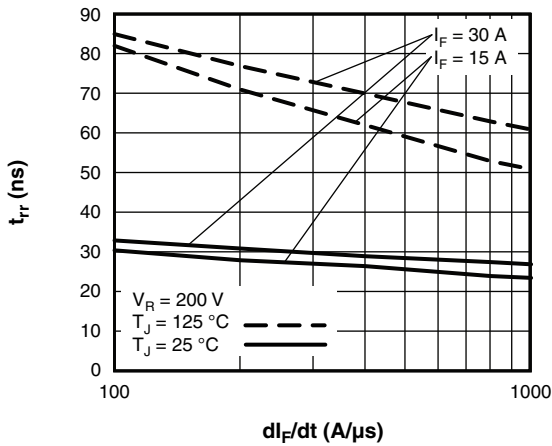


Fig. 7 - Typical Reverse Recovery Time vs. di_F/dt

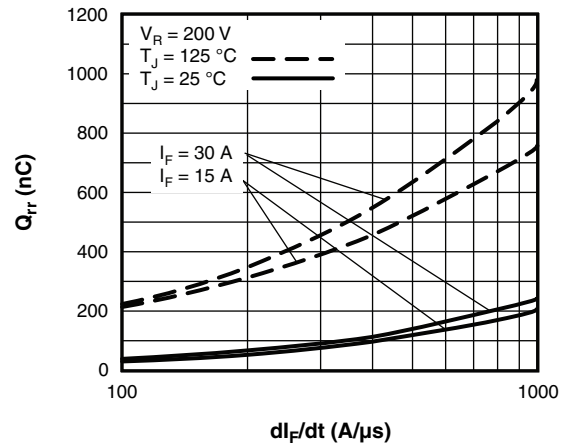
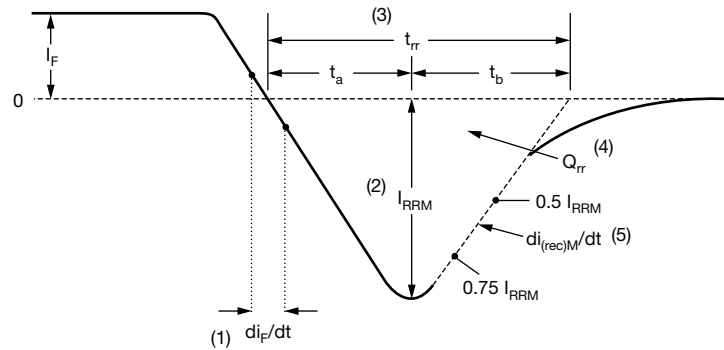


Fig. 8 - Typical Stored Charge vs. di_F/dt



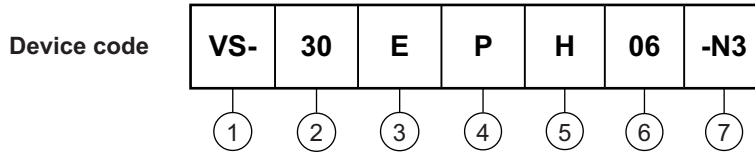
- (1) di_F/dt - rate of change of current through zero crossing
- (2) I_{RRM} - peak reverse recovery current
- (3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.
- (4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}
- (5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (30 = 30 A)
- 3** - Circuit configuration:
E = single diode
- 4** - Package:
P = TO-247AC
- 5** - H = hyperfast recovery
- 6** - Voltage rating (06 = 600 V)
- 7** - Environmental digit:
-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

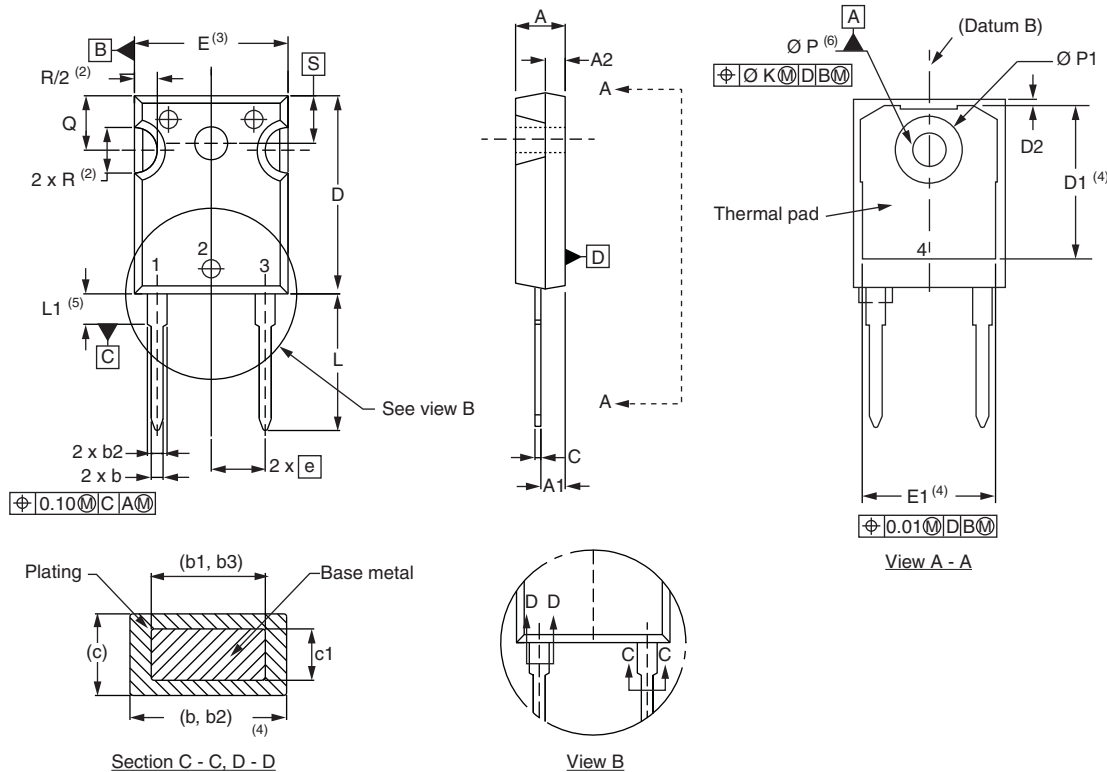
ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-30EPH06-N3	25	500	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?96144
Part marking information	www.vishay.com/doc?95648
SPICE model	www.vishay.com/doc?96573



TO-247AC 2L

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.65	5.31	0.183	0.209		E	15.29	15.87	0.602	0.625	3
A1	2.21	2.59	0.087	0.102		E1	13.46	-	0.53	-	
A2	1.17	1.37	0.046	0.054		e	5.46 BSC		0.215 BSC		
b	0.99	1.40	0.039	0.055		$\text{ (M) } \text{ (M) } D \text{ (B) (M)}$	0.254		0.010		
b1	0.99	1.35	0.039	0.053		L	14.20	16.10	0.559	0.634	
b2	1.65	2.39	0.065	0.094		L1	3.71	4.29	0.146	0.169	
b3	1.65	2.34	0.065	0.092		$\text{ (M) } \text{ (M) } D \text{ (B) (M)}$	3.56	3.66	0.14	0.144	
c	0.38	0.89	0.015	0.035		$\text{ (M) } \text{ (M) } D \text{ (B) (M)}$	-	7.39	-	0.291	
c1	0.38	0.84	0.015	0.033		Q	5.31	5.69	0.209	0.224	
D	19.71	20.70	0.776	0.815	3	R	4.52	5.49	0.178	0.216	
D1	13.08	-	0.515	-	4	S	5.51 BSC		0.217 BSC		
D2	0.51	1.35	0.020	0.053							

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) $\text{ (M) } \text{ (M) } D \text{ (B) (M)}$ to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension Q



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